

Thermal RC network (Foster)

SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
₹ _{th(j-mb)}	thermal resistance from junction to mounting base		-	-	0.57	K/W
	Cth ₁	1.835E-04 F		Ą	t:	
	Cth ₂	1.308E-03 F		_ 	tj	
	Cth ₃	9.881E-04 F			_	
	Cth ₄	3.804E-03 F				1
	Cth ₅	1.211E-02 F		L L		1
	Cth ₆	2.411E-02 F				
	Cth ₇	5.977E-01 F		Г	$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$	
	Cth ₈	1.623E+02 F			$\int Rth_2 + Cth_2$	2
	Rth₁	4.855E-04 Ω				
	Rth ₂	9.542E-04 Ω		Г	5	
	Rth ₃	1.131E-02 Ω			Rth3 = Cth;	3
	Rth ₄	2.702E-02 Ω			┎╧╺╋╾╌┤	
	Rth₅	9.606E-02 Ω			\	
	Rth ₆	3.569E-01 Ω				4
	Rth ₇	8.813E-02 Ω		L l	,	+
	Rth ₈	1.348Ε-03 Ω	(Р		
						5
						6
					$\int Rth_7 \stackrel{\bullet}{=} Cth_7$	7
Part:	BUK969R3-100E					
Date:	11/4/2013					3
Nodel Rth	0.58 K/W			_	· • • · · · · · · · · · · · · · · · · ·	
	0.00 1000				t _{amb} 001aal76	_

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